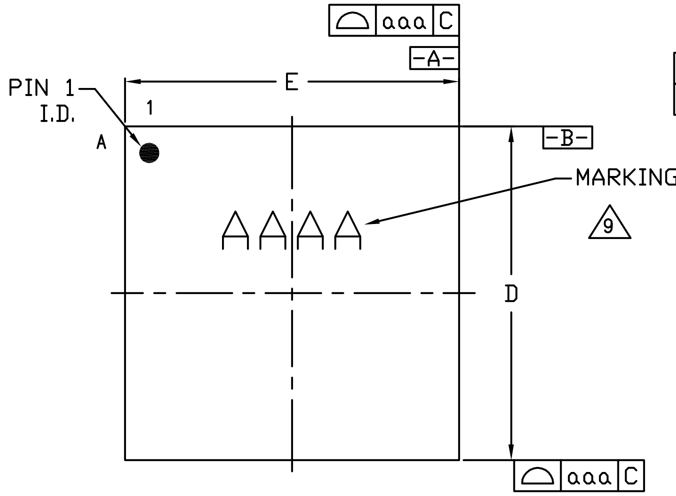
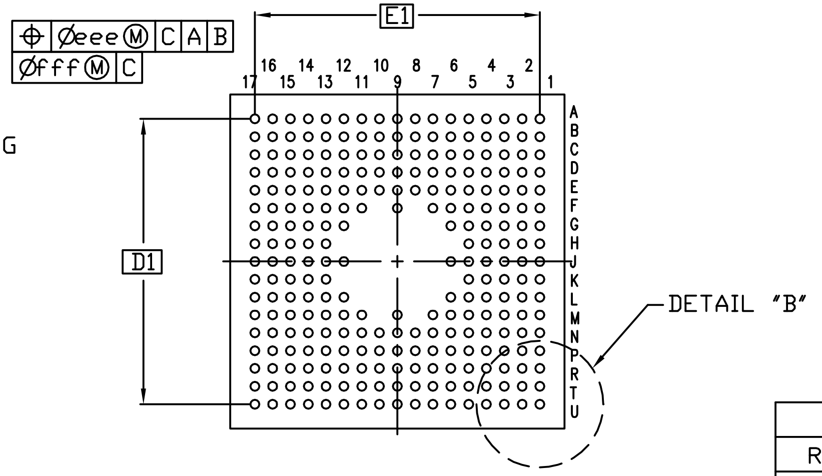
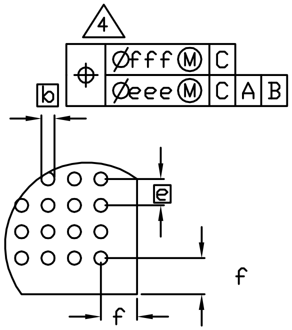


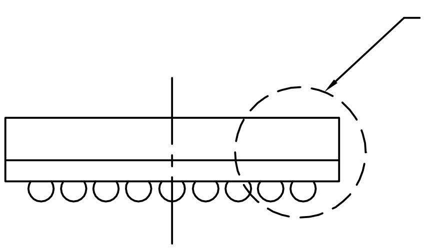
TOP VIEW



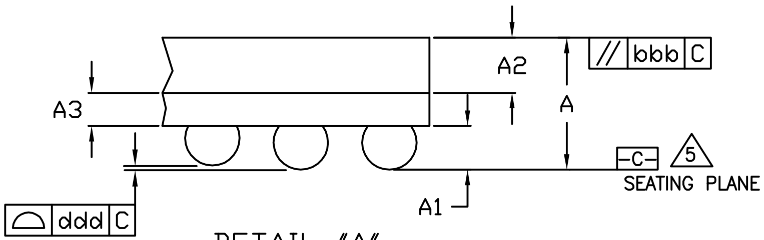
BOTTOM VIEW



DETAIL "B"



SIDE VIEW



DETAIL "A"

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. 'e' REPRESENTS THE BASIC SOLDER BALL PITCH.
3. 'M' REPRESENTS THE BASIC SOLDER BALL MATRIX SIZE. 'N' IS THE NUMBER OF ATTACHED SOLDER BALLS.
4. 'b' IS MEASURABLE AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO THE PRIMARY DATUM -C- .
5. PRIMARY DATUM -C- AND THE SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. THE PACKAGE SURFACE SHALL BE MATTE FINISH CHARMILLES 24 TO 27.
7. THE OVERALL PACKAGE THICKNESS "A" ALREADY CONSIDERS COLLAPSE BALLS.
8. REFERENCE JEDEC MO-205.
9. MARKING SHOWN IS FOR PKG. ORIENTATION ONLY.
10. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbFREE (+) PKG. CODES.
11. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131.

-DRAWING NOT TO SCALE-

DIMENSIONAL REFERENCES			
REF.	MIN.	NOM.	MAX.
A	1.25	1.40	1.50
A1	0.35	0.40	0.45
A2	0.65	0.70	0.75
A3	0.32 REF		
D	14.80	15.00	15.20
D1	12.80 BSC		
E	14.80	15.00	15.20
E1	12.80 BSC		
b	--	0.4	--
e	0.8 BSC		
f	--	1.10	--
aaa	--	--	0.15
bbb	--	--	0.10
ddd	--	--	0.10
eee	--	--	0.15
fff	--	--	0.08
M	17		
N	256		
Pkg. Code: X25655-1, X25655-2			

MAXIM

TITLE:
PACKAGE OUTLINE,
256 BALLS CSBGA, 15x15x1.4 mm

APPROVAL	DOCUMENT CONTROL NO.	REV.	
EDEN CHEN 5/3/10	21-0446	C	1/1